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UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.
NOTES PRECEDED BY AN UNMARKED "□" ARE NOT APPLICABLE.

REVISIONS		DATE	APPROVED
ZONE	LTR	DESCRIPTION	

1. APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS, IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES, IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.

2. HOLE SIZE APPLY AFTER PLATING, TOLERANCE TO BE +/- .003.

3. REGISTRATION TOLERANCE: ARTWORK +/- .002
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.

4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH, FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.

5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: □ SINGLE SIDED, □ DOUBLE SIDED, □ MULTI-LAYER (SEE DETAIL 'A')
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL, FINISHED BOARD THICKNESS: .062 +/- .10%

6. MANUFACTURER'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.

7. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT), COLOR: RED (0.001 TO 0.002" THICK OVER METAL).

8. SILKSCREEN □ TOP SIDE, □ BOTH SIDES, USING □ YELLOW, □ WHITE NPI LEADFREE, REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.

9. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.

10. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH, MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.

11. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

12. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

13. ALL OUTER LAYERS USING A 12.0 mil TRACE WIDTH SHALL BE 50ohms SINGLE ENDED, +/- 10% TOLERANCE.

ALL OUTER LAYERS USING A mil TRACE WIDTH SHALL BE 100ohms SINGLE ENDED, +/- 10% TOLERANCE.

ALL OUTER LAYERS USING A 6.0 mil TRACE WIDTH AND 5.0 mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 10% TOLERANCE.

ALL INNER LAYERS USING A 5 mil TRACE WIDTH AND 7 mil SPACING SHALL BE 100 ohms DIFFERENTIAL, +/- 10% TOLERANCE.

14. MINIMUM COPPER CONDUCTOR WIDTH IS: 5MIL.

MINIMUM COPPER SPACING IS: 4.5MIL.

15. SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.

16. GROUND ETCH ON ALL LAYERS TO BOARD EDGE IS INTENTIONAL. DO NOT PULL BACK.

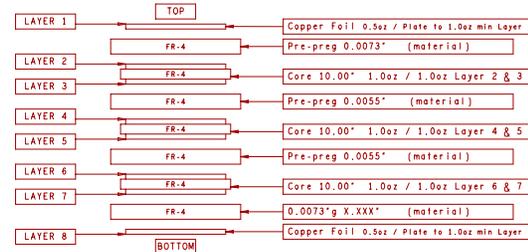
17. NO CHANGES TO ANY ARTWORK ARE PERMITTED WITHOUT WRITTEN AUTHORIZATION.

18. HOLES SIZE APPLIES AFTER PLATING. TOLERANCE TO BE +/- .003/- .010.

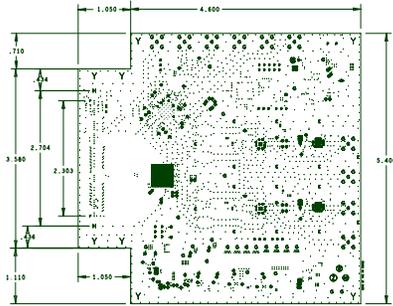
19. FILL VIAS IN PAD (INCLUDING VIAS UNDER BGA, EXCEPT VIAS IN THERMAL PAD UNDER IC'S) WITH NON CONDUCTIVE MATERIAL.

20. FINISHED BOARDS MUST BE RoHS COMPLIANT AND SURVIVE A LEAD FREE ASSEMBLY, MAXIMUM REFLOW TEMPERATURE OF 260 DEGREE C (6 PASSES).

DETAIL 'A'



DRILL CHART: TOP TO BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
+	6.0	PLATED	64
-	8.0	PLATED	32
-	8.0	PLATED	196
-	10.0	PLATED	2242
+	12.0	PLATED	138
+	13.0	PLATED	18
+	15.0	PLATED	8
+	38.0	PLATED	31
+	53.0	PLATED	16
+	59.0	PLATED	10
o	62.0	PLATED	23
o	67.0	PLATED	40
u	68.0	PLATED	2
⊙	120.0	PLATED	2
⊙	140.0	PLATED	1
+	40.0	NON-PLATED	2
+	45.0	NON-PLATED	2
Y	125.0	NON-PLATED	8



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING	
MATERIAL SEE NOTE 5	DRAWN	L. NGUYEN	TSW30H84 EVM	
	ENGR	K. HSIA		
FINISH SEE NOTES 7, 8, 9			SIZE B	REV. A
DO NOT SCALE DRAWING			SCALE NONE	SHEET 1 OF 1